NOTE 4

NOTE 6

Α

888

TOP VIEW

SIDE VIEW

NOTE 8 D2 > <u>A A A A IA A A A A IA A A A</u>

В

NOTE 6

D

0.20 C

NOTE 5

0.10 C

0.10 C

 $|\triangle|$

24X

E1

PIN 1— REFERENCE

e →

⊕ 0.15 M C A-B D



SSOP24 NB EP CASE 940AP ISSUE O

0.20 C A-B

Н

△ 0.20 C

2X 12 TIPS

C SEATING PLANE

NOTE 8

⊕ | 0.15 M | C | A-B

⊕ 0.12 M C A-B D

A2

D

E

12

24X b

DATE 05 MAR 2015

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME
- LOCATED ON THE LOWER RADIUS OF THE FOOT. DIMENSION & APPLIES TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 TO 0.25 FROM THE LEAD TIP.
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS, MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION D IS
- 5. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH
- 6. DATUMS A AND B ARE DETERMINED AT DATUM

	MILLIMETERS			
DIM	MIN	MAX		
Α		1.75		
A1	0.00 0.10			
A2	1.10	1.65		
b	0.19	0.30		
С	0.09	0.20		
D	8.64 BSC			
D2	2.37	2.67		
Е	6.00 BSC			
E1	3.90 BSC			
E2	1.79	1.99		
е	0.65	0.65 BSC		
h	0.25	0.50		
L	0.40	0.85		
L1	1.00 REF			
L2	0.25 BSC			
M	0°	8°		

L2

GAUGE PLANE

C SEATING PLANE

DETAIL A

DETAIL A

END VIEW

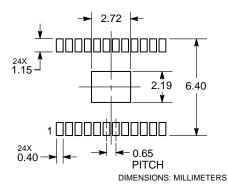
- Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS. DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.10 MAX. AT MMC. DAMBAR CANNOT BE
- DETERMINED AT DATUM PLANE H.
- OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE. DIMENSION E1 IS DETERMINED AT DA-TUM PLANE H.
- PLANE H.
 7. A1 IS DEFINED AS THE VERTICAL DISTANCE
- FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- CONTOURS OF THE THERMAL PAD ARE UN-CONTROLLED WITHIN THE REGION DEFINED BY DIMENSIONS D2 AND E2.

	MILLIMETERS			
DIM	MIN	MAX		
Α		1.75		
A1	0.00	00 0.10		
A2	1.10 1.65			
b	0.19 0.30			
С	0.09	0.20		
D	8.64 BSC			
D2	2.37	2.67		
Е	6.00 BSC			
E1	3.90 BSC			
E2	1.79	1.99		
е	0.65 BSC			
h	0.25	0.50		
L	0.40	0.85		
L1	1.00 REF			
L2	0.25 BSC			
М	0°	8°		

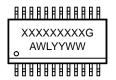
RECOMMENDED SOLDERING FOOTPRINT

H H H H H H H H H H H

BOTTOM VIEW



GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code Α = Assembly Location WL

= Wafer Lot YY = Year WW = Work Week G = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking.

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